

Replacement Abstract

A method 10, 80, 81 for making multi-layer electronic circuit boards 77, 137, 139 having metallized apertures 18, 20, 34, 40, 104, 106, 120 [[.]], the method 10, 80, 81 includes the steps of: providing an electrically conductive member 82; forming apertures 88, 90, 91 within the member 82; applying an adhesive material 92 to the member 82, such that adhesive material 92 fills the aperture 88, 90, 91; coupling electrically conductive members 94, 96 to member 82, thereby forming a pre-circuit assembly, wherein each member 94, 96 includes a pair of apertures 111, 113 and 115, 117, respectively; electroplating apertures 104, 106 with a first conductive material 108; and disposing a second conductive material 143 within aperture 120, thereby creating a multi-layer circuit board.